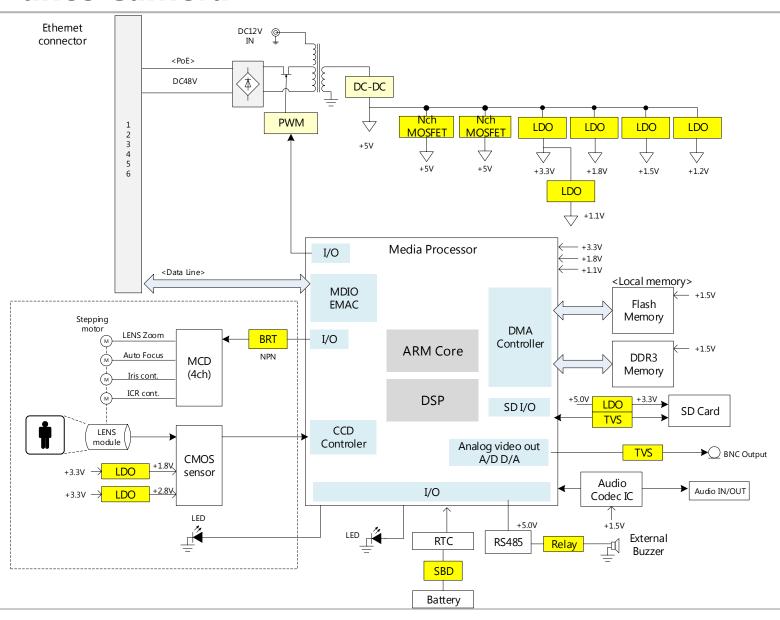


Surveillance Camera Application Block Diagram - ABD -

Toshiba Electronic Devices & Storage Corporation Discrete Application Engineering Center

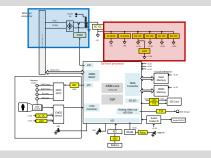
ABD – Surveillance Camera



Power supply line Recommended Devices

Navigation Window

Мар

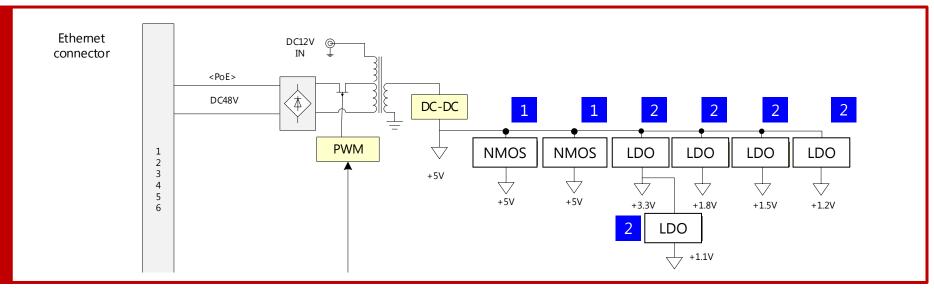


Tips for Device Selection

The VDSS rating is important in selecting MOSFETs. Application of a voltage exceeding VDSS might result in the destruction of a MOSFET.

MOSFETs with high VDSS ratings tend to have large on-state resistance, RDS(ON).

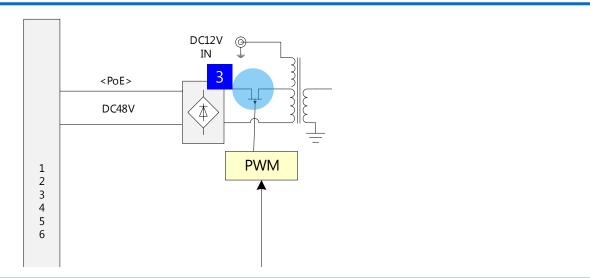
Power Supply



Ethemet

connector

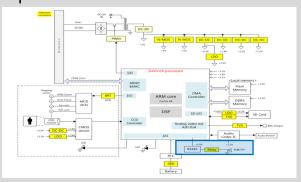
Power Supply



Analog Signal line Recommended Devices

Navigation Window

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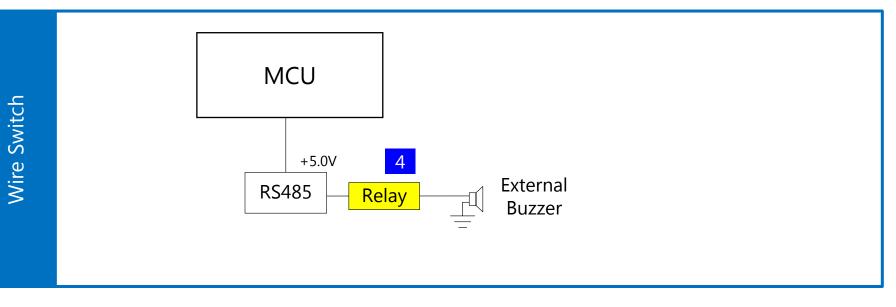
Tips for Device Selection



LED current, output voltage of MCU and base-emitter voltage, DC current gain of the transistor are important in selecting transistor for LED drive.



Small package saves board space

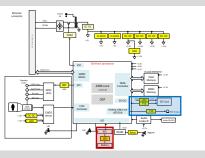


Power supply line Recommended Devices

Power Supply

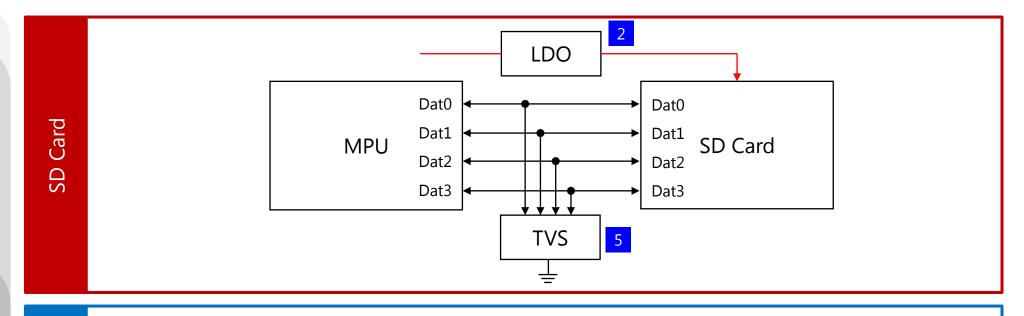
Navigation Window

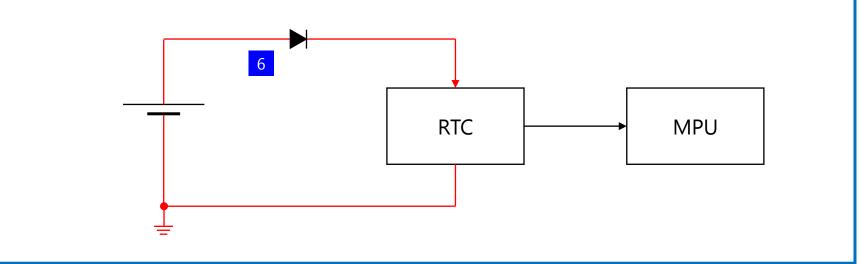
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Tips for Device Selection

- PSRR is key performance of LDO for SD memory card interface
- TVS diodes for protecting high-speed signal lines from external ESD.
- Low VF and Low IR are needed for SBD





MOSFET 1 3

Device Type		MOSFET	MOSFET
Proposal Product		SSM3K376R	TPH5900CNH
Package			
		SOT-23F	SOP Advance
	Size [mm]	2.9×2.4×0.8	10×28×4.5
	Polarity	N-ch	N-ch
ţi	VDSS [V]	30	150
erisi	ID [A]	4(DC)	9(DC)
acte	PD [W]	1	42
Characteristic	Ciss (Typ) [pF]	200	460
	RDS(ON) (Max) [mΩ]	56 at VGS=4.5V	59 at VGS=10V
VGSMerit		1.8V drive	Small R _{DS(ON)} High-speed switching

LDO Regulator

n	
4	

Device Type		LDO	
Proposal Product		TCR2FE series	
Package		A Park	
		SMV	
	Size [mm]	2.9×2.8×1.1	
	VIN (Max) [V] 6.0		
tic	VOUT [V]	1.0 to 5.0	
eris	IOUT (Min) [A]	0.2	
act	PD [W]	0.58	
Characteristic	IB (Typ) [μA]	35	
	R.R. (Typ) [dB]	73	
Merit		Low drop out	

Recommendation for Mechanical Relay Replacement

|--|

Characteristics	TLP3107	TLP3555A	TLP3556A	
Package	2.54SOP6 (6.3×7.0×2.1 mm)	DIP4 (4.58×7.62×3.65 mm)		
Forward voltage (VF) @IF=10mA	1.18V(min), 1.33(typ), 1.48V(max)	1.5V(min), 1.64(typ), 1.8V(max)		
Contact arrangement	Normally opened (1-Form-A)			
On-state resistance (RON)	60mΩ	(100m Ω)	200mΩ	
Diode power dissipation (PD)	50mW	50mW	50mW	
Off-state output terminal voltage (VOFF)	60V	60V	100V	
Turn-ON time (tON)	Max. 5.0 ms	Max. 2.0 ms	Max. 2.0 ms	
Turn-OFF time (tOFF)	Max 1.0 ms	Max 1.0 ms	Max 0.5 ms	
Operating temperature (Topr)	-40°C to +85°C -40°C to +110°C			
Comment	 In case of using 12/24VDC relay for Surveillance Camera, it is possible to recommend of Toshiba photo relays(VOFF=600VDC, 100VDC). Using DIP4, 2.54SOP6 package, it will be more smaller size of thermostat. 			

Device Type		Photorelay	Photorelay	Photorelay
Proposal Product		TLP3107	TLP3555A	TLP3556A
Package				
		2.54 SOP6 DIP4		DIP4
	Size [mm]	6.3×7.0×2.1	4.58×7.62×3.65	4.58×7.62×3.65
	Contact arrangement	Normally opened (1-Form-A)	Normally opened (1-Form-A)	Normally opened (1-Form-A)
Characteristic	ION (max)[A]	3.3	3.0	2.0
	VOFF (max) [V]	60	60	100
	RON (typ.) [mΩ]	60	100	200
	BVS (max) [Vrms]	1500	2500	2500

Device Type		TVS diode	TVS diode
Proposal Product		DF10G5M4N	DF10G6M4N
Package		DFN10	DFN10
	Size [mm]	2.5 x 1.0	2.5 x 1.0
	Number of bit	4	4
tic	V _{ESD} [kV]	±20	±20
teris	V _{RWM} (Max) [V]	3.6	5.5
Characteristic	C _t (Typ) [pF]	0.2	0.2
S S	$R_{DYN}(Typ) [\Omega]$	0.5	0.5
	V _C @1A(Typ) [V]	7.5	8.5

Schottky Barrier Diode

Device Type			SBD	SBD
Proposal Product			CUS10F30	CTS05F40
Package				
		SOD-323	SOD-882	
	Size [mm]		2.5 x 1.25	1.0 x 0.6
	I _O (Max) [A]		1.0	0.5
ristic	V _R (Max) [V]		30	40
Characteristic	V _F [V] @VR(Max)	Тур.	0.43	0.74
		Max.	0.50	0.81
	I _R [μA] Max.		50	15

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